

## **Technical Data Sheet**

#### MODEL NO: S196ANB4

0603Package 1.6\*0.6\*1.2mm Chip LEDs

Features :

•Package in 8mm tape on 7" diameter reel

•Compatible with automatic placement equipment

•Compatible with reflow solder process

Applications:

Indicators

•Automotive : backlighting in dashboard and switch

•Backlight for LCD

Dice material	Emitted color	Lens Color
InGaN	Blue	Water Clear

### Electrical/Optical Characteristics(Ta=25°C)

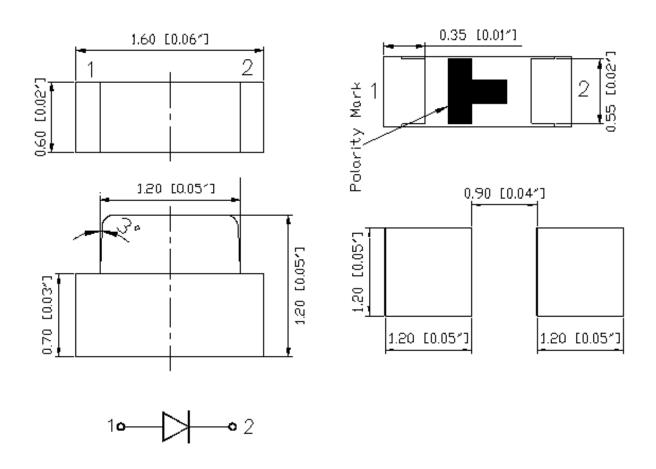
Parameter	Test	Symbol	Value			Unit	
	Condition		Min	Тур	Max	Unit	
Dominant wavelength	IF=5mA	λD	В	465	470	475	nm
Forward voltage	IF=5mA	VF	В	2.5	3.0	3.4	V
Luminous intensity	IF=5mA	lv	В	12.5	24	40	mcd
Viewing angle at 50% Iv	IF=10mA	2 <i>θ</i> 1/2	В		140		Deg
Reverse current	VR=5V	lr	В			10	μΑ

#### Absolute Maximum Ratings(Ta=25°C)

Parameter	Symbol	Value	Unit
Power dissipation	Pd	102	mW
Forward current	lf	30	mA
Reverse voltage	VR	5	V
Operating temperature range	Тор	-40 ~+80	°C
Storage temperature range	Tstg	-40 ~+85	°C
Peak pulsing current (1/8 duty f=1kHz)	FP	125	mA



# PACKAGING DIMENSIONS (mm):



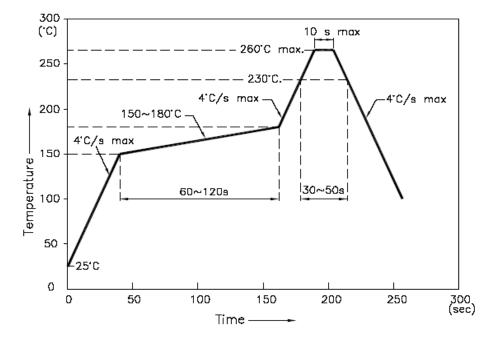
#### 17May15D

condition is :  $60^{\circ}C \pm 5^{\circ}C$  for 15hrs.

Precautions For Use :	
Over – current – proof	
Customer must apply resistors for protection, otherwise slight voltage shift will cause big	
current change (Burn out will happen)	
Storage	
1. The operation of temperature and R.H. are $:5^{\circ}C \sim 30^{\circ}C$ , 60% R.H. Max.	
2. Once the package is opened, the products should be used within a week. Otherwise, they should	
be kept in a dampproof box with desiccating regent. Considering the tape life, we suggest our	
customers to use our products within 1.5 year (from production date).	
3. It's recommended to bake before soldering when the package is unsealed after 72 hrs. The	



■ Reflow Temp/Time



#### NOTES:

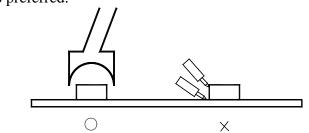
- 1. We recommend the reflow temperature  $245^{\circ}C(\pm 5^{\circ}C)$ .the maximum soldering temperature should be limited to  $260^{\circ}C$ .
- 2. dont cause stress to the epoxy resin while it is exposed to high temperature.
- 3. Number of reflow process shall be 2 times or less.

#### ■Soldering iron

Basic spec is  $\leq$  5sec when 260°C. If temperature is higher, time should be shorter (+10°C  $\rightarrow$  -1sec ).Power dissipation of iron should be smaller than 20W, and temperatures should be controllable .Surface temperature of the device should be under 230°C .

#### ■Rework

- 1. Customer must finish rework within 5 sec under  $260^{\circ}$ C.
- 2. The head of iron can not touch copper foil
- 3. Twin-head type is preferred.



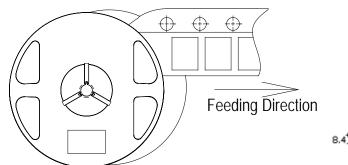
■ Avoid rubbing or scraping the resin by any object, during high temperature, for example reflow 、 solder etc.

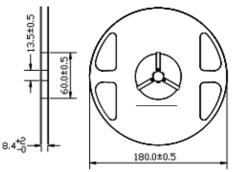


## Packaging specifications

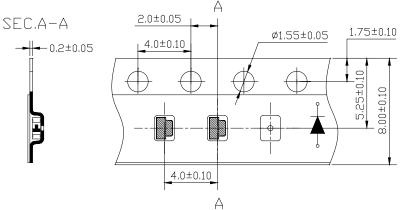
## • Feeding Direction

• Dimensions of Reel (Unit: mm)





### • Dimensions of Tape (Unit: mm)



### • Arrangement of Tape

